

IN THE SPECIFICATION

Please amend the Abstract as follows:

A conductive particle 30 ~~which can be used for connecting a variety of adherends, is provided,~~
~~and the~~ The conductive particle 30 includes a resin particle 31, a first conductive particle
disposed around the resin particle, 31, a first resin coating 25 disposed on the periphery thereof
of the resin particle. The first resin coating being ~~and softer than the resin particle, 31, and a~~ A
second conductive thin film 36 is ~~is~~ disposed therearound, ~~and if~~ When the surface part of, ~~for~~
~~example,~~ an electrode 13 of an adherend that is to be connected is hard, a first resin coating of
the conductive particle 35 and the second conductive thin film 36 are destroyed by pressure to
bring the second conductive thin film 36 in contact with the electrode 13 and a metal wiring 17.
If the surface part of the electrode 13 is soft, the second conductive thin film on the surface side
comes in contact with the electrode 13, which makes it possible for the particle to be used
regardless of the surface state of an adherend, ~~in other words, be used for connecting a variety~~
~~of adherends~~